Monolithically Integrated Rad-Hard SiC Gate Driver for 1200 V DMOSFETs, Phase II

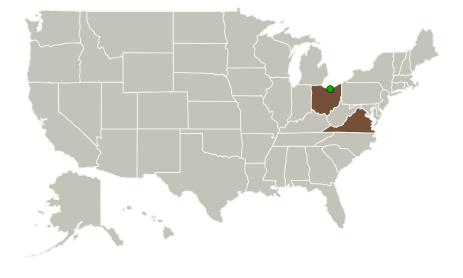


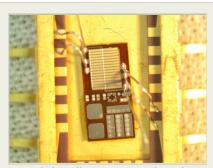
Completed Technology Project (2017 - 2019)

Project Introduction

This two-phase SBIR program targets the need for highly integrated SiC-based electronics systems by developing gate drive circuitry that can be fully integrated with 4H-SiC power switching devices, enabling eventual realization of a monolithic power switching platform. Specifically, the final goal of this program is to develop and demonstrate a fully integrated, isolated gate driver architecture, having an integrated SiC power MOSFET. In addition to integrated resistors and capacitors, development of SiC CMOS technology will entail the demonstration of lateral SiC NMOSFETs and the more challenging SiC PMOSFET devices with adequate performance and radiation hardness. During Phase I, an NMOS-only gate drive buffer circuit was designed and implemented on the same host substrate used for fabricating 1200 V SiC DMOSFETs. Phase II will focus on integrating the gate drive buffer IC fabricated during Phase I with a 1200 V rated power SiC DMOSFET. Process and device development of a SiC PMOS technology will be conducted during Phase II, in pursuit of a SiC CMOS gate drive circuit. The fabricated power and lateral SiC devices will be subjected to extensive radiation testing to investigate the degradation pathways of this monolithic power switching device, when exposed to high radiation environments.

Primary U.S. Work Locations and Key Partners





Monolithically Integrated Rad-Hard SiC Gate Driver for 1200 V DMOSFETs, Phase II

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Small Business Innovation Research/Small Business Tech Transfer

Monolithically Integrated Rad-Hard SiC Gate Driver for 1200 V DMOSFETs, Phase II



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Organizations Performing Work	Role	Туре	Location
GeneSiC Semiconductor Inc.	Lead Organization	Industry Minority-Owned Business, Small Disadvantaged Business (SDB)	Dulles, Virginia
Glenn Research Center(GRC)	Supporting Organization	NASA Center	Cleveland, Ohio

Primary U.S. Work Locations	
Ohio	Virginia

Project Transitions

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June 2017: Project Start

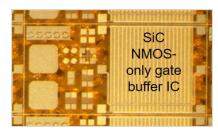


December 2019: Closed out

Closeout Documentation:

• Final Summary Chart(https://techport.nasa.gov/file/140856)

Images



Briefing Chart Image

Monolithically Integrated Rad-Hard SiC Gate Driver for 1200 V DMOSFETs, Phase II Briefing Chart Image (https://techport.nasa.gov/imag

Organizational Responsibility

Responsible Mission Directorate:

Space Technology Mission Directorate (STMD)

Lead Organization:

GeneSiC Semiconductor Inc.

Responsible Program:

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Project Management

Program Director:

Jason L Kessler

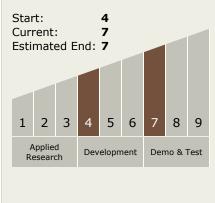
Program Manager:

Carlos Torrez

Principal Investigator:

Ranbir Singh

Technology Maturity (TRL)





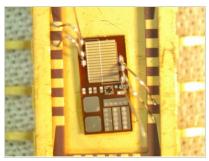
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Completed Technology Project (2017 - 2019)



Final Summary Chart Image Monolithically Integrated Rad-Hard SiC Gate Driver for 1200 V DMOSFETs, Phase II (https://techport.nasa.gov/imag e/135032)

Technology Areas

Primary:

- TX03 Aerospace Power and Energy Storage
 TX03.3 Power Management and Distribution
 TX03.3.1 Management
 - TX03.3.1 Management
 and Control

Target Destinations

The Sun, Earth, The Moon, Mars, Others Inside the Solar System, Outside the Solar System

